

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hideki FUKUSHIMA</td> <td>02/28/2013</td> </tr> <tr> <td>Nobuaki HIROSE</td> <td>03/14/2013</td> </tr> </tbody> </table>		Name	Execution Date	Hideki FUKUSHIMA	02/28/2013	Nobuaki HIROSE	03/14/2013		
Name	Execution Date								
Hideki FUKUSHIMA	02/28/2013								
Nobuaki HIROSE	03/14/2013								
RECEIVING PARTY DATA									
<table border="1"> <tr> <td>Name:</td> <td>HITACHI HIGH-TECHNOLOGIES CORPORATION</td> </tr> <tr> <td>Street Address:</td> <td>24-14, Nishi Shimbashi 1-chome, Minato-ku</td> </tr> <tr> <td>City:</td> <td>Tokyo</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> </table>		Name:	HITACHI HIGH-TECHNOLOGIES CORPORATION	Street Address:	24-14, Nishi Shimbashi 1-chome, Minato-ku	City:	Tokyo	State/Country:	JAPAN
Name:	HITACHI HIGH-TECHNOLOGIES CORPORATION								
Street Address:	24-14, Nishi Shimbashi 1-chome, Minato-ku								
City:	Tokyo								
State/Country:	JAPAN								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13821468</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13821468				
Property Type	Number								
Application Number:	13821468								
CORRESPONDENCE DATA									
Fax Number: 7036841157 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 7036841120 Email: jmartinez@mmiplaw.com Correspondent Name: Mattingly & Malur, PC Address Line 1: 1800 Diagonal Road Address Line 2: Suite 370 Address Line 4: Alexandria, VIRGINIA 22314									
ATTORNEY DOCKET NUMBER:	KAS-8718								
NAME OF SUBMITTER:	Douglas R. Hanscom								
Signature:	/Douglas R. Hanscom/								
Date:	04/23/2013								
Total Attachments: 1 source=8718-Assignment#page1.tif									

CH \$40.00 13821468

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI HIGH-TECHNOLOGIES CORPORATION, a corporation organized under the laws of Japan, located at 24-14, Nishi Shimbashi 1-chome, Minato-ku, Tokyo 105-8717 Japan receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

DEFECT INSPECTING APPARATUS AND DEFECT INSPECTING METHOD

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI HIGH-TECHNOLOGIES CORPORATION.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Hideki Fukushima</u> Hideki FUKUSHIMA	<u>H.F. 2/28/2013</u> 28/2/2013 2/28/2013
2) <u>Nobuaki Hirose</u> Nobuaki HIROSE	<u>3/14/2013</u>
3) _____	_____
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____